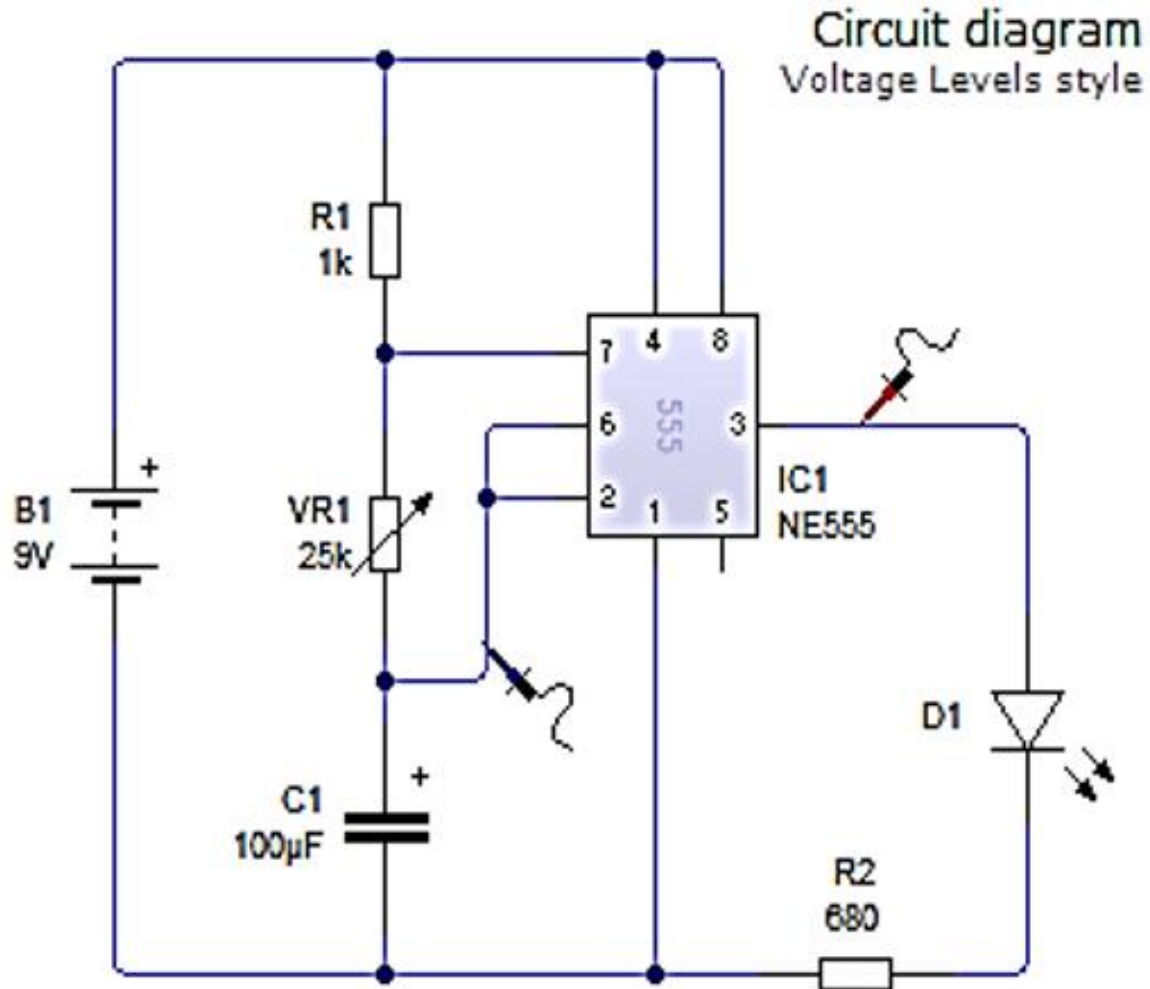


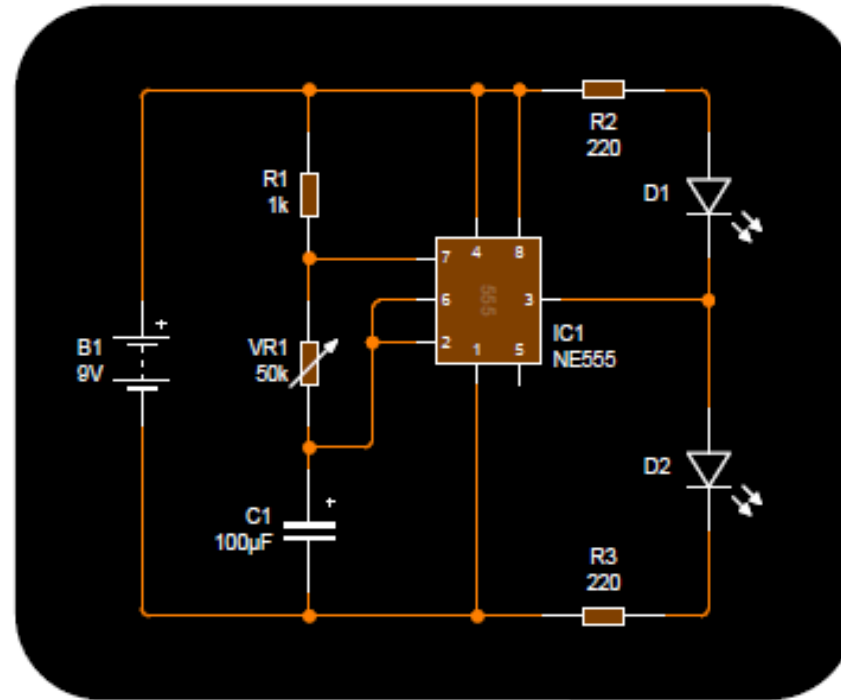
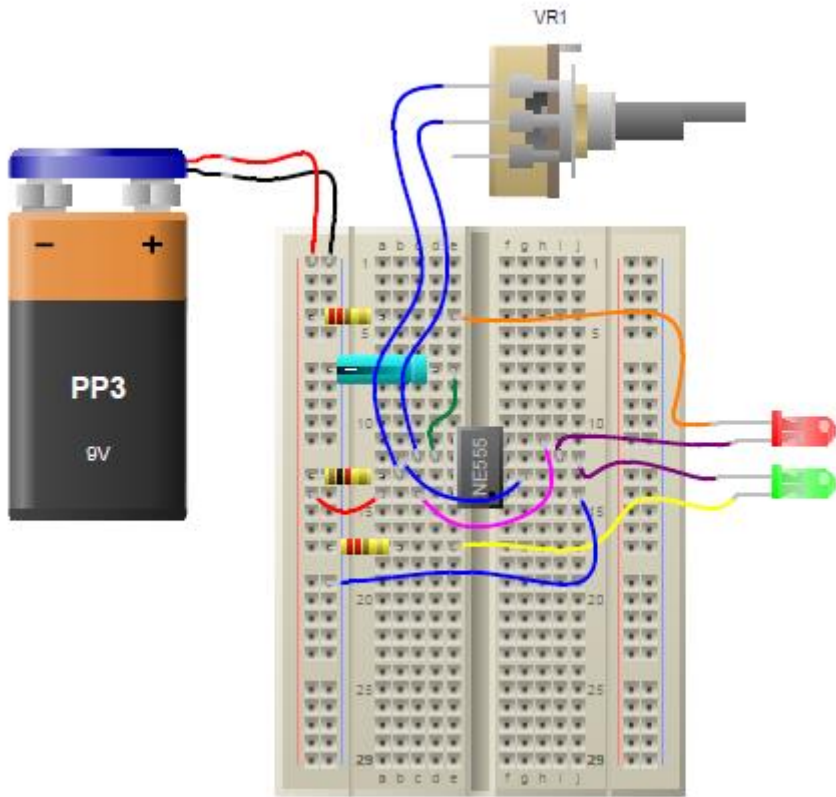
Nombres y Apellidos: _____ Grado y Sección: _____

Práctica calificada 1- ejer-01



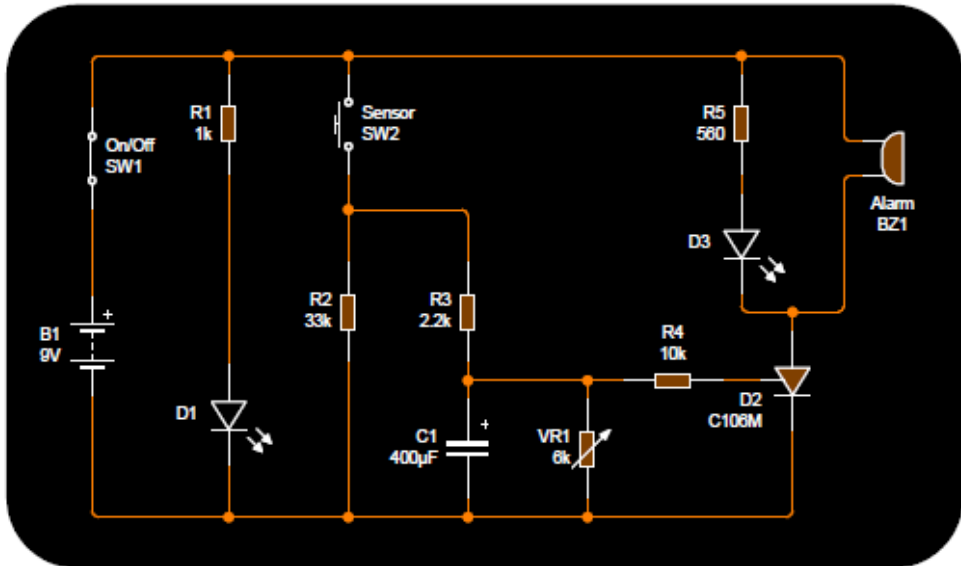
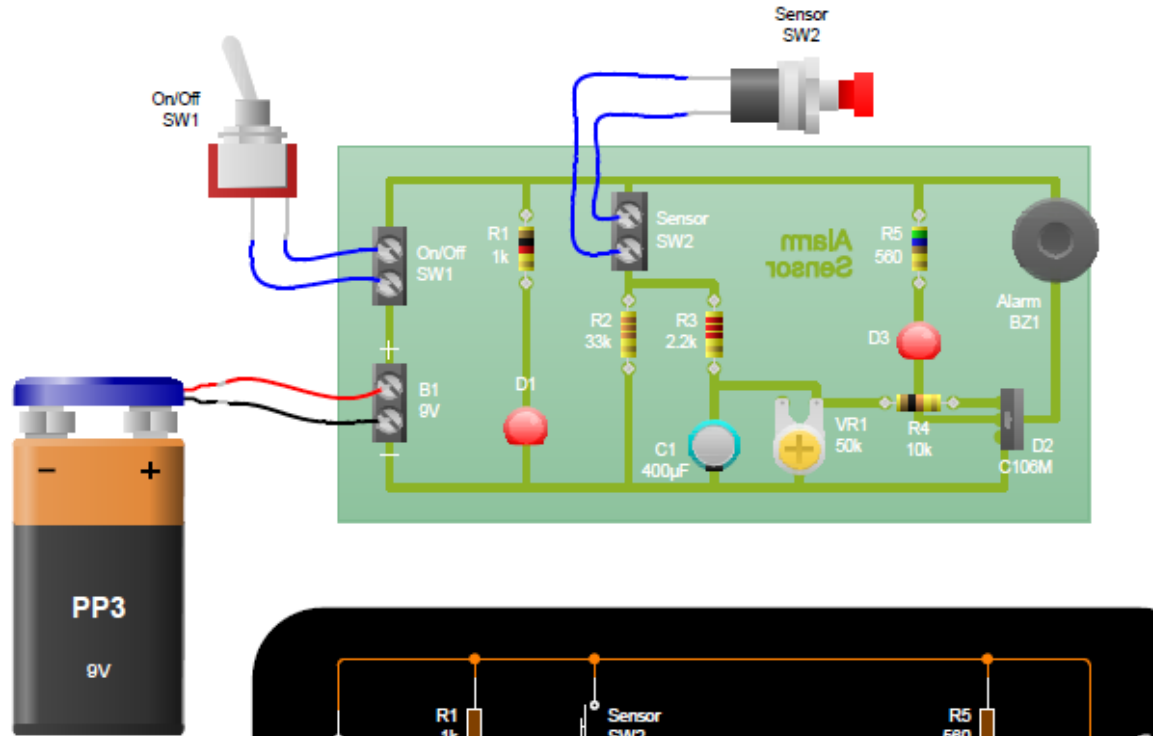
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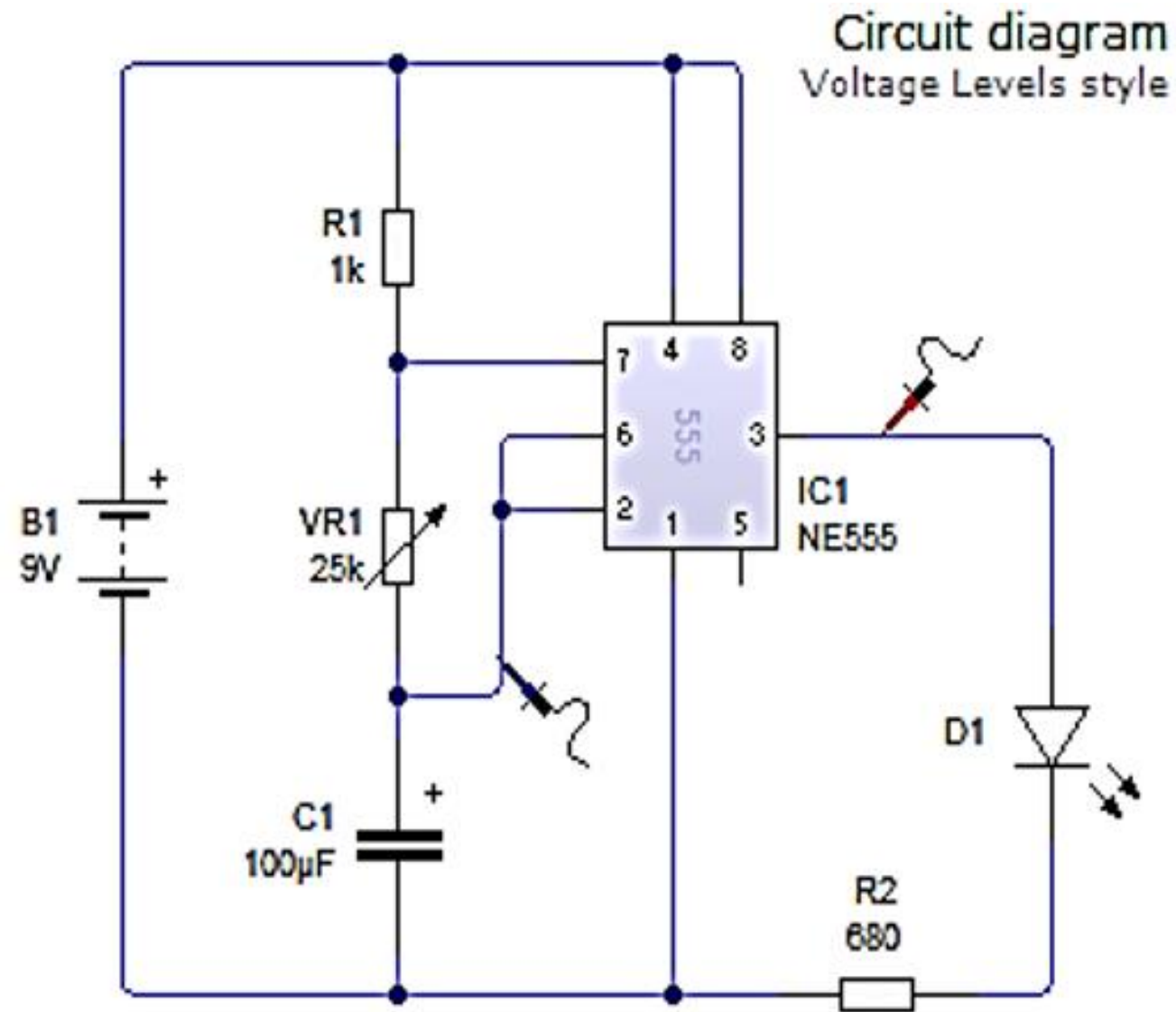


Nombres y Apellidos: _____ Grado y Sección: _____

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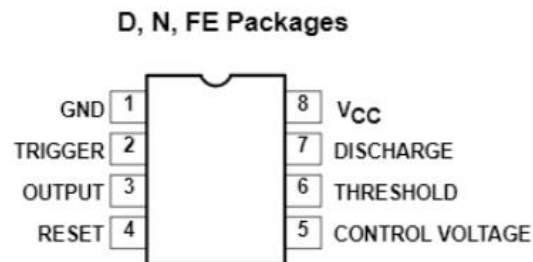


Nombres y Apellidos: _____ Grado y Sección: _____



NE/SA/SE555/SE555C

PIN CONFIGURATIONS



Timer

NE/SA/SE555/SE555C

ABSOLUTE MAXIMUM RATINGS

SYMBOL	PARAMETER	RATING	UNIT
V_{CC}	Supply voltage		
	SE555	+18	V
	NE555, SE555C, SA555	+16	V
P_D	Maximum allowable power dissipation ¹	600	mW
T_A	Operating ambient temperature range		
	NE555	0 to +70	°C
	SA555	-40 to +85	°C
	SE555, SE555C	-55 to +125	°C
T_{STG}	Storage temperature range	-65 to +150	°C
T_{SOLD}	Lead soldering temperature (10sec max)	+300	°C

NOTES:

- The junction temperature must be kept below 125°C for the D package and below 150°C for the FE, N and F packages. At ambient temperatures above 25°C, where this limit would be derated by the following factors:

D package 160°C/W
FE package 150°C/W
N package 100°C/W
F package 105°C/W

BLOCK DIAGRAM

